600 V / 4.5 A, High and Low Side Automotive Gate Driver IC

Description

The FAN7191 / FAD7191 is a monolithic high- and low-side gate-driver IC, which can drive high speed MOSFETs and IGBTs that operate up to +600 V. It has a buffered output stage with all NMOS transistors designed for high pulse driving capability and minimum cross-conduction.

ON Semiconductor's high-voltage process and common-mode noise canceling technique provide stable operation of high-drivers under high dV/dt noise circumstances. An advanced level-shift circuit allows high-side gate driver operation up to $V_S = -9.8 \ V$ (typical) for $V_{BS} = 15 \ V$.

The UVLO circuit prevents malfunction when V_{DD} and V_{BS} are lower than the specified threshold voltage.

The high current and low output voltage drop features make this device suitable for controlling direct injection actuators and for use in many automotive DC-DC converter and motor control applications.

Features

- Floating Channel for Bootstrap Operation to +600 V
- 4.5 A Sourcing and 4.5 A Sinking Current Driving Capability
- Common-Mode dV/dt Noise Cancelling Circuit
- Built-in Under-Voltage Lockout for Both Channels
- Matched Propagation Delay for Both Channels
- 3.3 V and 5 V Input Logic Compatible
- Output In-phase with Input
- 14–SOP with Separate Signal and Power Ground for Enhanced Noise Immunity
- 14–SOP with Increased Clearance for High Voltage Applications
- Automotive Applications, AEC Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Electric and Hybrid Electric Vehicles
- 48 V Mild Hybrid Vehicles
- Automotive High Voltage DC-DC converters
- Motor Control (Fans, Pumps, Compressors)
- Advanced Fuel Injection Systems
- Starter/Alternator
- Electric Power Steering
- MOSFET and IGBT Driver Applications



ON Semiconductor®

www.onsemi.com



SOIC8 CASE 751EB



SOIC14 CASE 751EF

ORDERING INFORMATION

Part Number	Package	Shipping
FAN7191MX-F085	8-SOP (751EB)	2500 / Tape & Reel
FAD7191M1X	14-SOP (751EF)	2500 / Tape & Reel

Typical Application Circuit

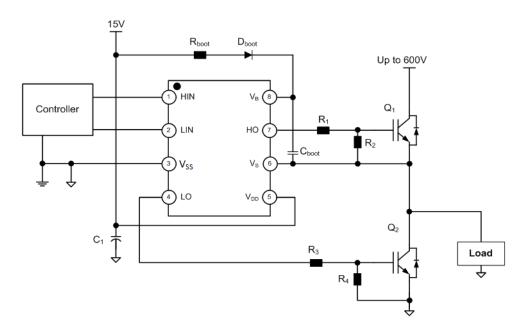


Figure 1. Half-Bridge Application Circuit (8-SOP)

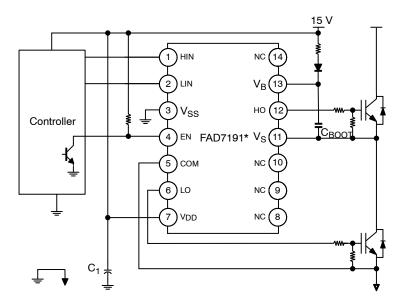


Figure 2. Half-Bridge Application Circuit (14-SOP)

INTERNAL BLOCK DIAGRAM

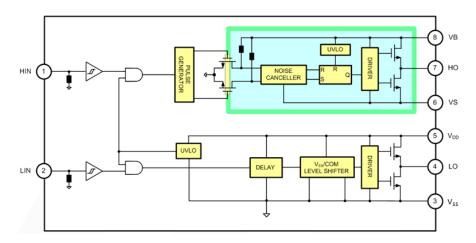


Figure 3. Functional Block Diagram (8-SOP)

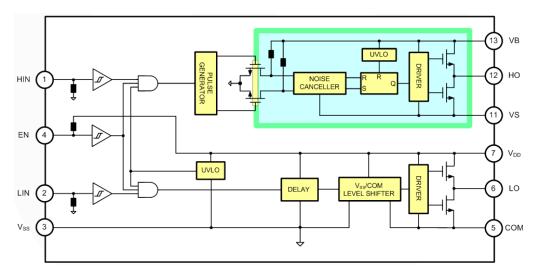


Figure 4. Functional Block Diagram (14-SOP)

Pin Assignment

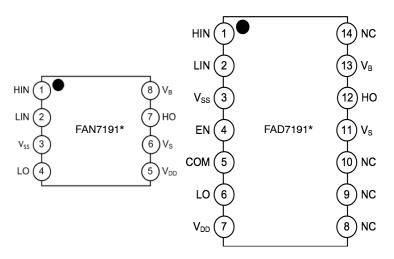


Figure 5. Pin Assignments (Top View)

Table 1. PIN DEFINITIONS

8-Pin	14-Pin	Name	Description	
1	1	HIN	Logic Input for High-Side Gate Driver Output	
2	2	LIN	Logic Input for Low-Side Gate Driver Output	
3	3	V _{SS}	Logic Ground, Power ground for 8–SOP	
	4	EN	Enable Input (Internal Pull Up)	
	5	СОМ	Power Ground for 14–SOP, Low–side Driver Return	
4	6	LO	Low-Side Driver Output	
5	7	V_{DD}	Low-Side and Logic Power Supply Voltage	
6	11	V _S	High-Side Floating Supply Return	
7	12	НО	High-Side Driver Output	
8	13	V _B	High-Side Floating Supply	
	8, 9, 10, 14	NC	No Connect	

Table 2. ABSOLUTE MAXIMUM RATINGS

 $(T_A = -40^{\circ}C \text{ to } 125^{\circ}C, \text{ unless otherwise specified. } V_B, V_{DD} \text{ and } V_{IN} \text{ are referenced to } V_{SS})$

Symbol		Parameter		Min.	Max.	Unit
V _S	High-side offset voltage VS			V _B – 25	V _B + 0.3	V
V _B	High-side floating sup	pply voltage VB		-0.3	625	V
V _{HO}	High-side floating out	put voltage		V _S – 0.3	V _B + 0.3	V
V_{DD}	Low-side and logic-fix	xed supply voltage		-0.3	25	V
СОМ	Power Ground (14–SC	OP)		V _{DD} – 25	V _{DD} + 0.3	V
V _{IN}	Logic Input voltage (H	IN, LIN, EN)		-0.3	V _{DD} + 0.3	V
V_{LO}	Low-Side Output Volta	age LO (8-SOP)		V _{SS} – 0.3	V _{DD} + 0.3	V
	Low-Side Output Voltage LO (14-SOP)			COM - 0.3	V _{DD} + 0.3	V
T _{pulse} (Note 4)	Minimum Pulse Width			80		ns
d _{VS/dt}	Allowable offset voltag	ge slew rate			50	V/ns
P _D	1 / /		8-SOP		0.625	W
(Note 1, 2, 3)			14-SOP		0.80	W
θ_{JA}	Thermal Resistance, j	unction-to-ambient	8-SOP		200	°C/W
(Note 1, 2)			14-SOP		156	°C/W
T _J	Junction temperature				+150	°C
T _S	Storage temperature		-55	+150	°C	
ESD	Electrostatic	Human Body Model,	8-SOP		3000	V
	Discharge Capability	ty JESD22-A114	14-SOP		2000	
		Charged Device Model, JESD22-C101			2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Mounted on $76.2 \times 114.3 \times 1.6$ mm PCB (FR-4 glass epoxy material).
- 2. Refer to the following standards: JESD51-2: Integral circuits thermal test method environmental conditions natural convection. JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages.
- 3. P_D is the power that raises T_J to 150°C for T_A = 25°C. P_D to be derated at higher ambient temperature.
- 4. Minimum input pulse width that guarantee to produce an output pulse. Valid for turn on and turn off pulse width.

Table 3. RECOMMENDED OPERATING CONDITIONS (V_S , V_{DD} and V_{IN} are referenced to V_{SS})

Symbol	Parameter	Min.	Max.	Unit
V _B	High-side floating supply voltage	V _S + 10	V _S + 22	V
V _S	High-side Floating Supply Offset Voltage	6 – V _{BS}	600	V
V _{HO}	High-side Output Voltage	V _S	V _B	V
V_{DD}	Low-side and Logic Supply voltage	10	22	V
V	Low-side output voltage (8-SOP)	0	V_{DD}	V
V_{LO}	Low-side output voltage (14-SOP)	СОМ	V_{DD}	V
V _{IN}	Logic input voltage (HIN, LIN, EN)	0	V_{DD}	V
СОМ	Power Ground (14–SOP)	V _{DD} – 22	V_{DD}	V
T _A	Ambient Temperature	-40	+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. ELECTRICAL CHARACTERISTICS

 $(V_{BIAS}~(V_{DD},~V_{BS})$ = 15.0 V, V_S = V_{SS} = COM, T_A = -40°C to 125°C, unless otherwise specified. The V_{IL} , V_{IH} and I_{IN} parameters are referenced to V_{SS} and are applicable to the respective input signals HIN and LIN. The V_O and I_O parameters are referenced to COM (or V_{SS} in case of 8-SOP). V_S and COM (V_{SS} for 8-SOP) are applicable to the respective outputs HO and LO)

Symbol	Characteristic	Condition	Min.	Тур.	Max.	Unit
POWER SUPPLY	SECTION (V _{DD} AND V _{BS})		•	•		•
V _{DDUV+} V _{BSUV+}	V _{DD} and V _{BS} Supply Under-Voltage Positive-going Threshold		7.8	8.8	9.8	V
V _{DDUV} - V _{BSUV} -	V _{DD} and V _{BS} Supply Under–Voltage Negative Going Threshold		7.2	8.3	9.1	
V _{DDHYS}	V _{DD} supply under–voltage lockout hysteresis			0.5		
I _{LK}	Offset Supply Leakage Current	V _B = V _S = 600 V			50	μА
I _{QBS}	Quiescent V _{BS} Supply Current	V _{IN} = 0 V or 5 V		45	110	
I _{QDD}	Quiescent V _{DD} Supply Current	V _{IN} = 0 V or 5 V		75	150	
I _{PBS}	Operating V _{BS} Supply Current	f _{IN} = 20 kHz, RMS value (See Figure 26)		400	800	μА
I _{PDD}	Operating V _{DD} Supply Current	f _{IN} = 20 kHz, RMS value (See Figure 26)		400	800	
LOGIC INPUT SE	CTION (HIN, LIN, EN)					•
V _{IH}	Logic "1" Input Voltage		2.5			V
V _{IL}	Logic "0" Input Voltage				1.2	
I _{IN+}	Logic "1" Input Bias Current (HIN/LIN)	V _{IN} = 5 V		25	50	μΑ
I _{IN} _	Logic "0" Input Bias Current (HIN/LIN)	V _{IN} = 0 V		1.0	2.0	
I _{EN+}	Enable High Input Bias Current	EN = 5 V	-100	-50	-10	
I _{EN-}	Enable Low Input Bias Current	EN = 0 V	-140	-75	-20	
R _{IN}	Input Pull-down Resistance		100	200		kΩ
GATE DRIVER O	UTPUT SECTION (HO, LO)					
V _{OH}	High-level Output Voltage, V _{BIAS} -V _O	No Load			1.35	V
V _{OL}	Low-level Output Voltage, VO	No Load			35	mV
I _{O+} (Note 5)	Output HIGH, Short-circuit Pulsed Current	$V_O = 0 \text{ V}, V_{IN} = 5 \text{ V} \text{ with}$ PW < 10 μ s	3.5	4.5		Α
I _{O-} (Note 5)	Output LOW Short-circuit Pulsed Current	$V_O = 15 \text{ V}, V_{IN} = 0 \text{ V} \text{ with}$ PW < 10 μs	3.5	4.5		
V _S	Allowable Negative V _S Pin Voltage for HIN Signal Propagation to HO	V _{BS} = 15V		-9.8	-9.0	V
COM-V _{SS} (Note 5)	Allowable COM-V _{SS} ground offset	14-SOP, V _{DD} = 15 V, V _{SS} = 0 V	-7.0			V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Parameters guaranteed by design.

Table 5. DYNAMIC ELECTRICAL CHARACTERISTICS

 $(V_{BIAS}\;(V_{DD},\,V_{BS})=15.0\;V,\,V_{S}\;=V_{SS}=COM=0\;V,\,T_{A}=-40^{\circ}C\;to\;125^{\circ}C,\,C_{LOAD}=1000\;pF\;unless\;otherwise\;specified)$

Symbol	Characteristic	Condition	Min.	Тур.	Max.	Unit
t _{on}	Turn-on Propagation Delay	V _S = 0 V		140	200	ns
t _{off}	Turn-off Propagation Delay	V _S = 0 V		140	200	ns
MT	Delay Matching				55	ns
t _r	Turn-on Rise Time			25	50	ns
t _f	Turn-off Fall Time			25	50	ns

Typical Characteristics

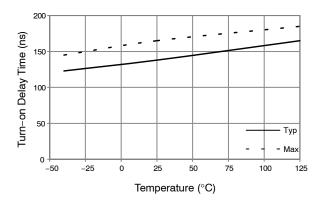


Figure 6. Turn-on Propagation Delay vs. Temperature

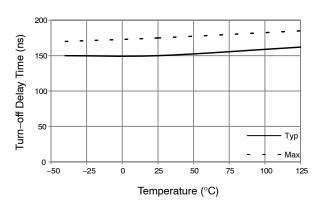


Figure 7. Turn-off Propagation Delay vs. Temperature

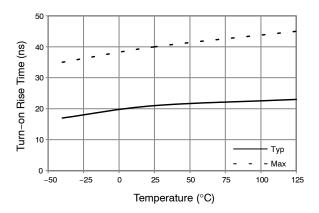


Figure 8. Turn-on Rise Time vs. Temperature

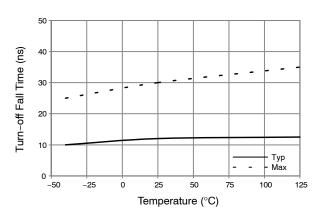


Figure 9. Turn-off Fall Time vs. Temperature

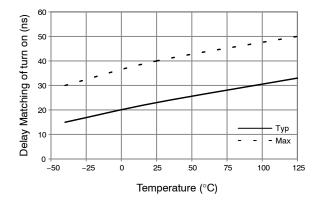


Figure 10. Turn-on Delay Matching vs. Temperature

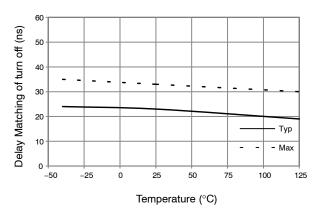
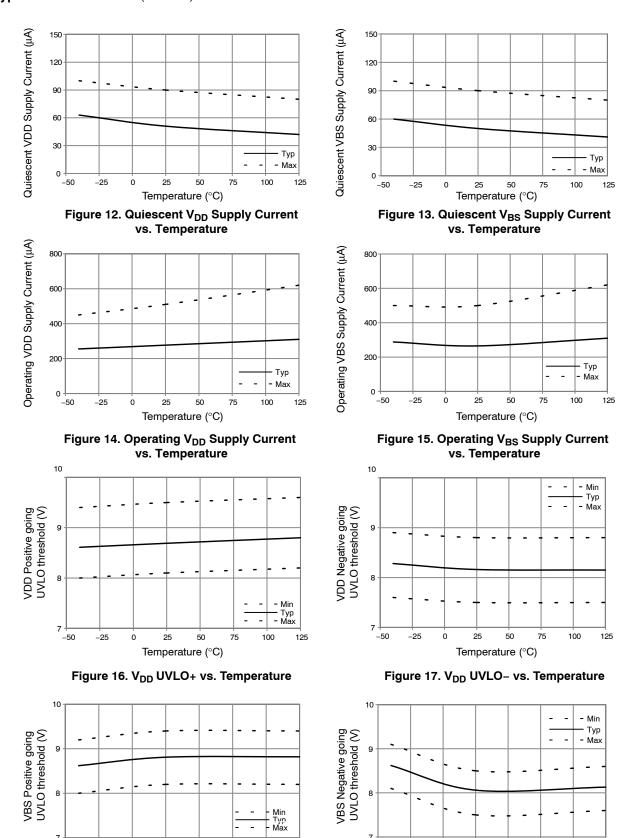


Figure 11. Turn-off Delay Matching vs. Temperature

Typical Characteristics (continued)



Temperature (°C) Figure 18. V_{BS} UVLO+ vs. Temperature

-50

-25

Temperature (°C)

Figure 19. V_{BS} UVLO- vs. Temperature

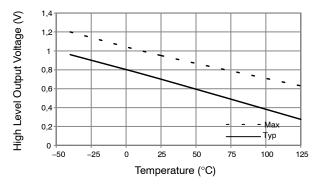
100

125

-50

-25

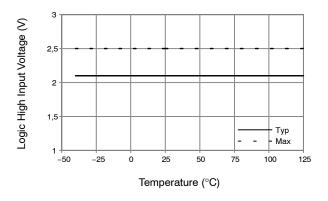
Typical Characteristics (continued)



0 0 25 0 25 0 25 0 125 Temperature (°C)

Figure 20. High-Level Output Voltage vs. Temperature

Figure 21. Low-Level Output Voltage vs. Temperature



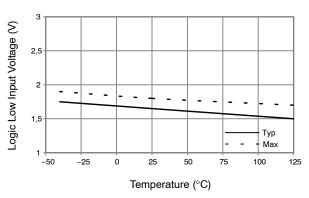
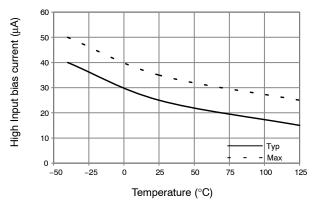


Figure 22. Logic High Input Voltage vs. Temperature

Figure 23. Logic Low Input Voltage vs. Temperature



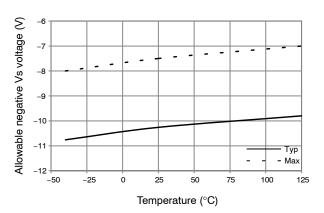


Figure 24. Logic "1" Input Bias Current vs. Temperature

Figure 25. Allowable Negative VS Voltage vs. Temperature

Switching Time Definitions

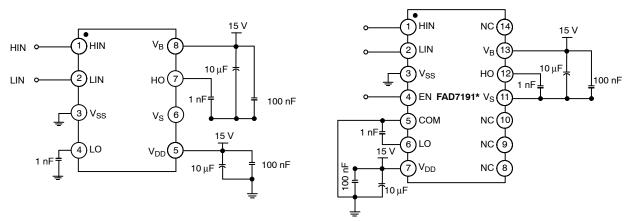


Figure 26. Switching Time Test Circuit

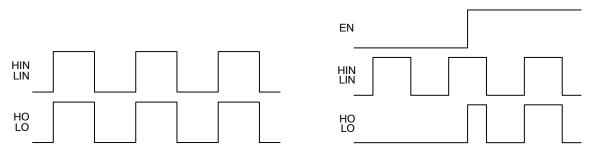


Figure 27. Input / Output Timing Diagram

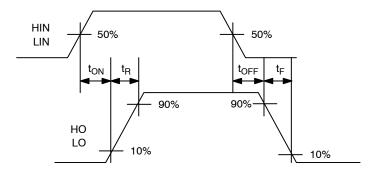


Figure 28. Switching Time Waveform Definitions

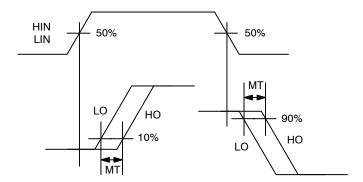
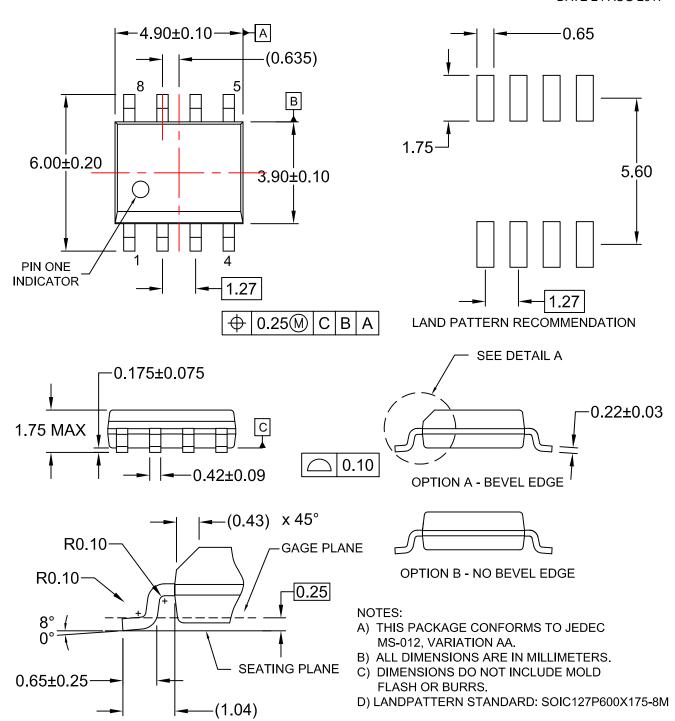


Figure 29. Delay Matching Waveform Definition

SOIC8 CASE 751EB ISSUE A

DATE 24 AUG 2017



DOCUMENT NUMBER:	98AON13735G	Electronic versions are uncontrolle accessed directly from the Document versions are uncontrolled except	'
STATUS:	ON SEMICONDUCTOR STANDARD		' '
NEW STANDARD:	NDARD:	"CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC8		PAGE 1 OF 2

DETAIL A
SCALE: 2:1



DOCUMENT NUMBER: 98AON13735G

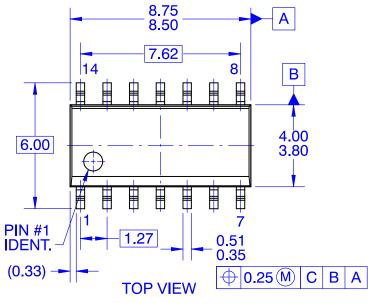
PAGE 2 OF 2

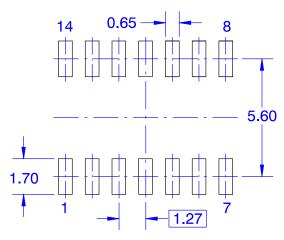
ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION FROM FAIRCHILD M08A TO ON SEMICONDUCTOR. REQ. BY B. MARQUIS.	30 SEP 2016
Α	CORRECTED DIMENSIONAL ERROR IN DETAIL A. REQ. BY H. ALLEN.	24 AUG 2017

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

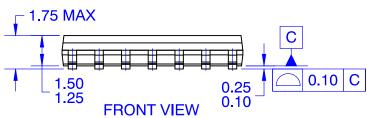
SOIC14 CASE 751EF **ISSUE O**

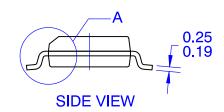
DATE 30 SEP 2016





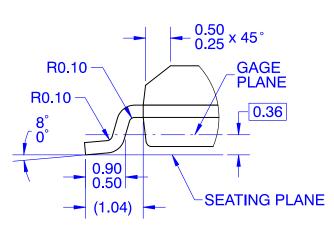
LAND PATTERN RECOMMENDATION





NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
 B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009



DETAIL A SCALE 16:1

DOCUMENT NUMBER:	98AON13739G	Electronic versions are uncontrolled except when
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped
NEW STANDARD:	IDARD:	"CONTROLLED COPY" in red.
DESCRIPTION:	SOIC14	PAGE 1 OF 2



DOCU	JMENT	NU	MB	ER:
98A0	N13739	G		

PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION FROM FAIRCHILD M14A TO ON SEMICONDUCTOR. REQ. BY B. MARQUIS.	30 SEP 2016

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. arising out of the application to use of any product or circuit, and specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death. associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor dates sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify a

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative